

TITLE: ETCANT FORMULATION FOR SELECTIVELY REMOVING THIN FILMS IN THE PRESENCE OF
COPPER, TIN, AND LEAD
INVENTORS NAME: Donald Danielson et al.
DOCKET NO.: 884.614US1

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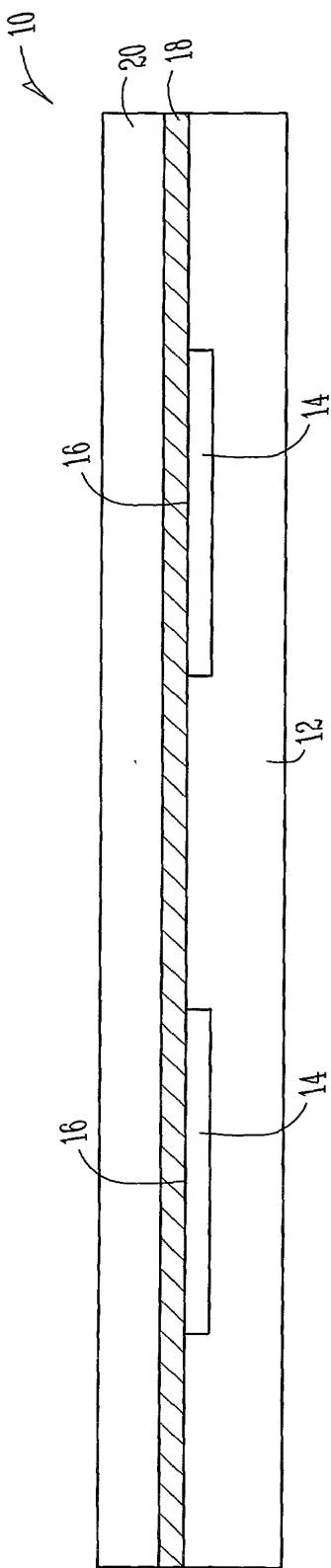


Fig. 1

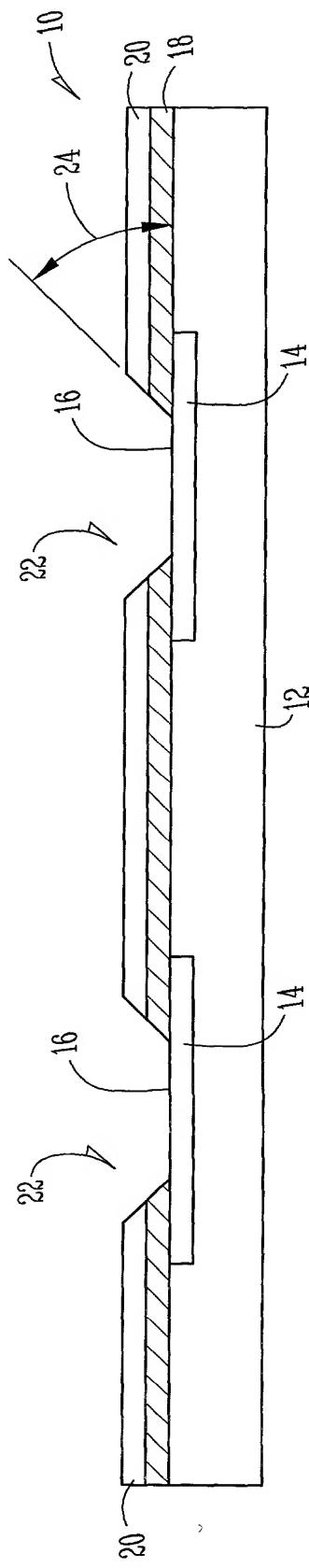


Fig. 2

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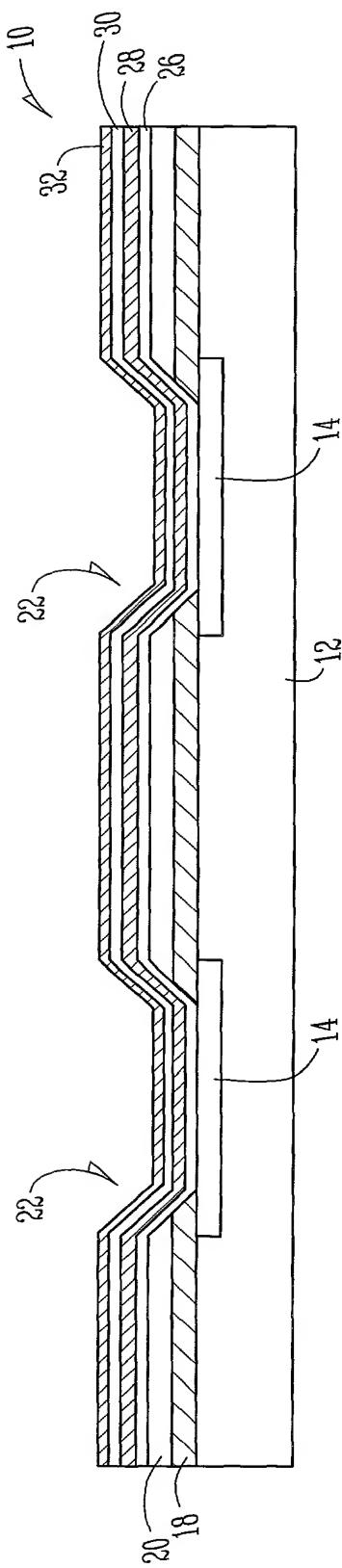


Fig. 3

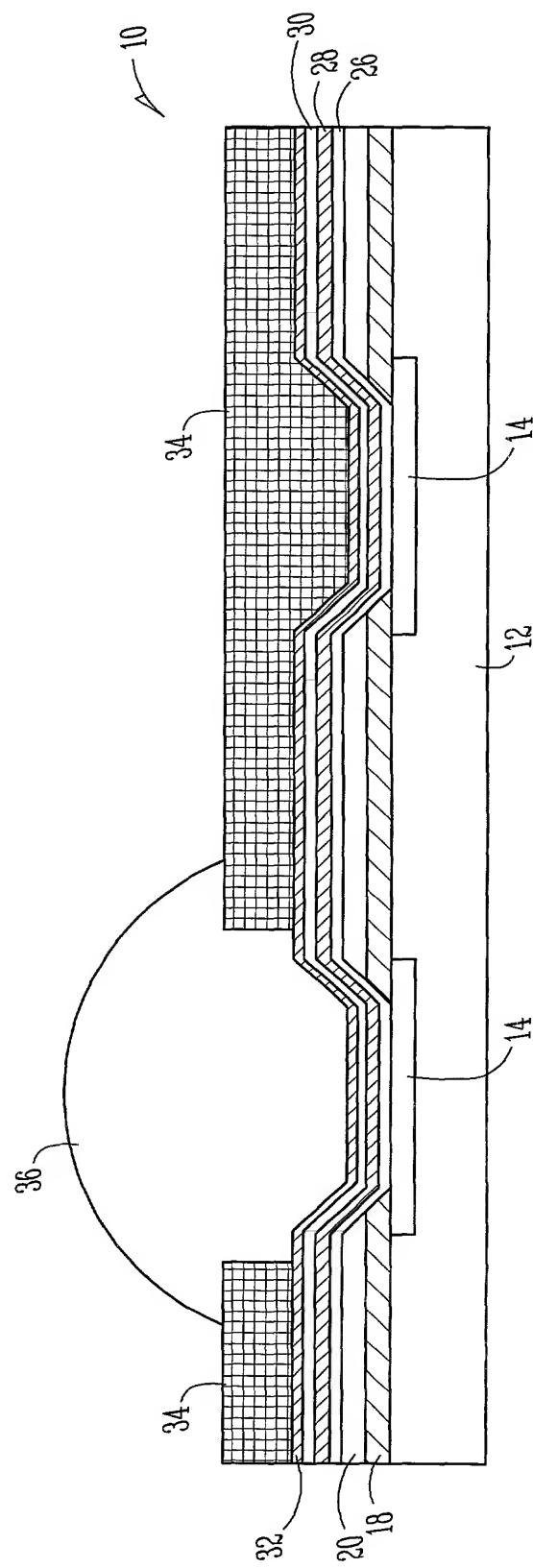


Fig. 4

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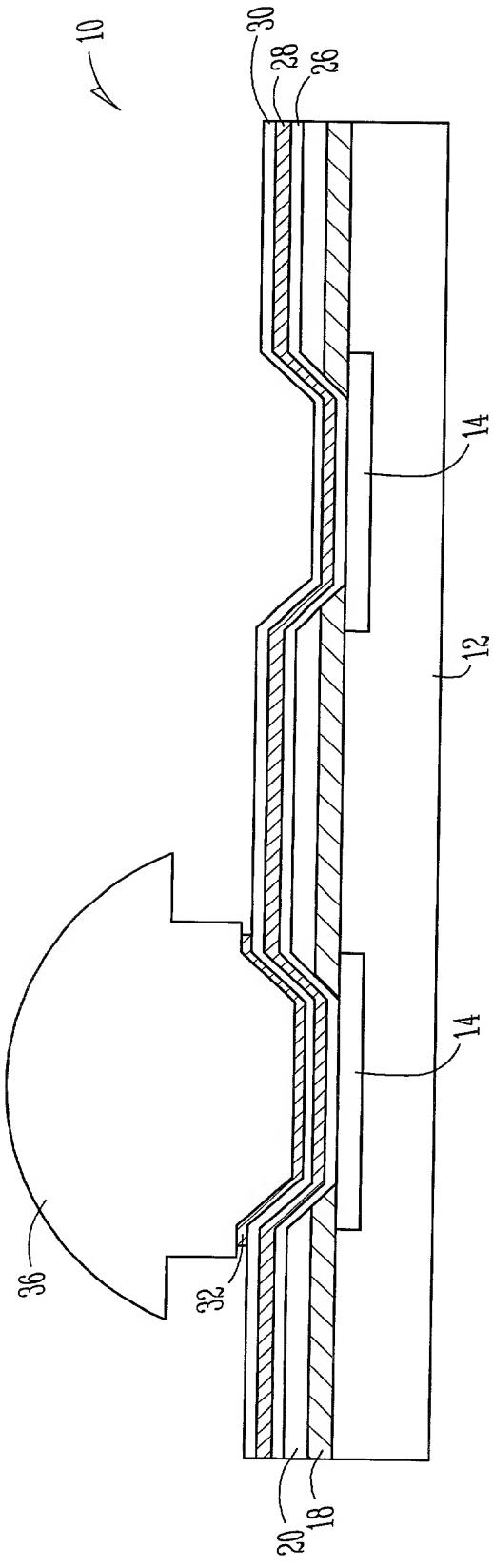


Fig. 5

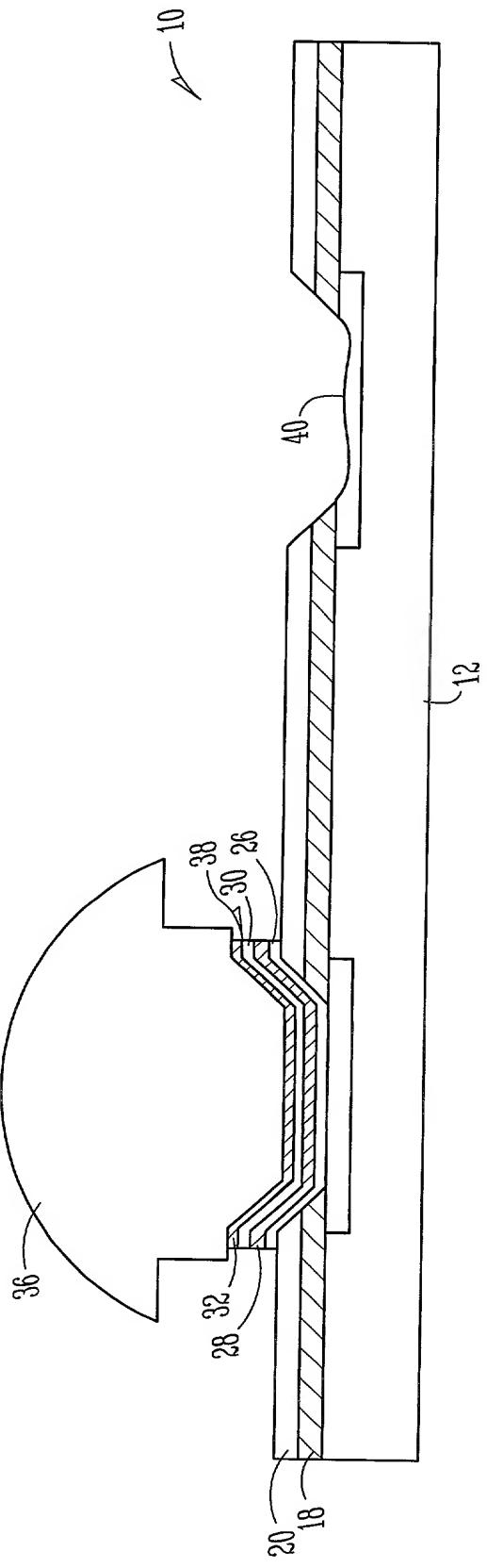


Fig. 6

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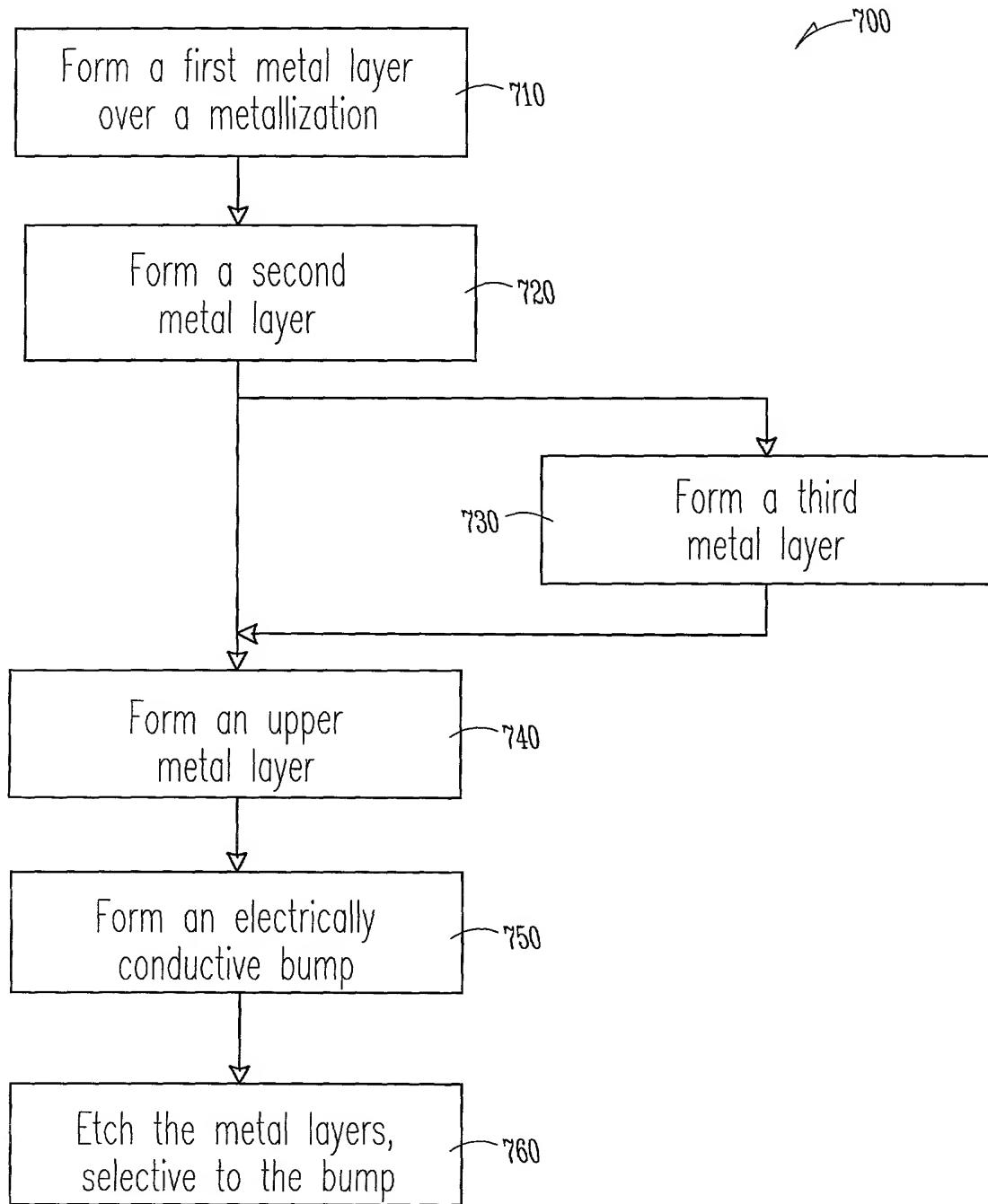


Fig. 7